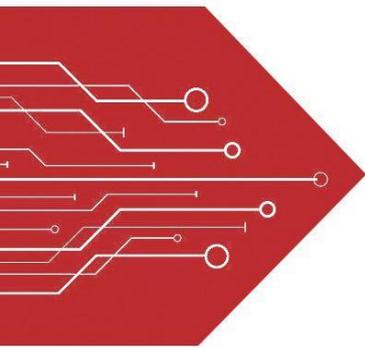
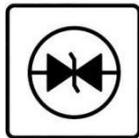


MSKSEMI

SEMICONDUCTOR



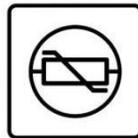
ESD



TVS



TSS



MOV



GDT



PLED

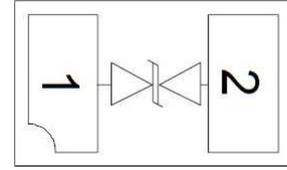
Product data sheet

Features

- 30W (8/20 μ s) Peak Pulse Power
- Low Capacitance ESD Protection
- RoHS Compliant
- Matte Tin Lead finish (Pb-Free)
- Protect One High Speed Data Line
- Meet IEC61000-4-2 Level 4:
- Contact Discharge > 8kV Air
- Discharge > 15kV

Applications

- Communication System
- Portable Instrumentation
- Audio and Video Equipment
- Computers and Peripherals
- USB 1.1, USB 2.0 Ports



DFN1006

Maximum Ratings (Ta = 25°C)

Symbol	Parameter	Value	Unit
PPK	Peak Pulse Power	30	W
IPP	Peak Pulse Current	2	A
VESD (Contact)	Contact ESD Voltage per IEC61000-4-2	8	kV
VESD (Air)	Air ESD Voltage per IEC61000-4-2	15	kV
TJ	Junction Temperature	-55 to +150	°C
TSTG	Storage Temperature	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VRWM	Reverse Working Peak Voltage				5	V
VBR	Reverse Breakdown Voltage	IT = 1mA	5.5		9.5	V
IR	Reverse Leakage Current	VRWM = 5V			0.1	μ A
VC	Clamping Voltage	IPP = 1A (8/20 μ s)			12	V
VC	Clamping Voltage	IPP = 2A (8/20 μ s)			15	V
CJ	Capacitance	VR = 0V, f = 1MHz		3.0	3.5	pF

Electrical Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T

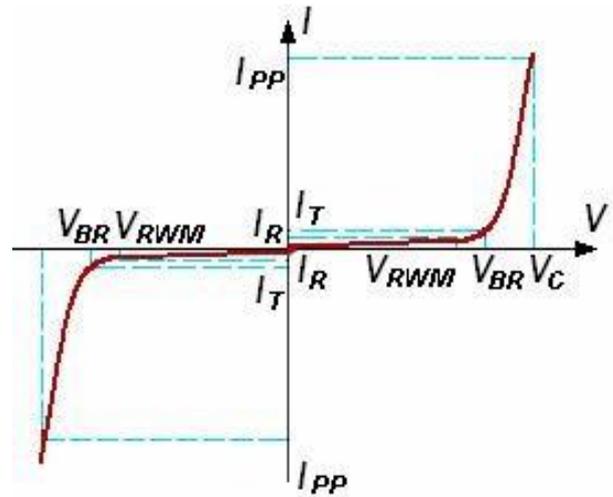


FIG1: Pulse Waveform

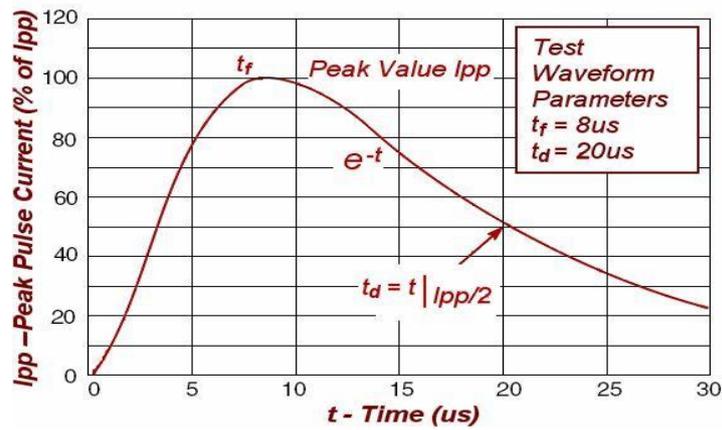
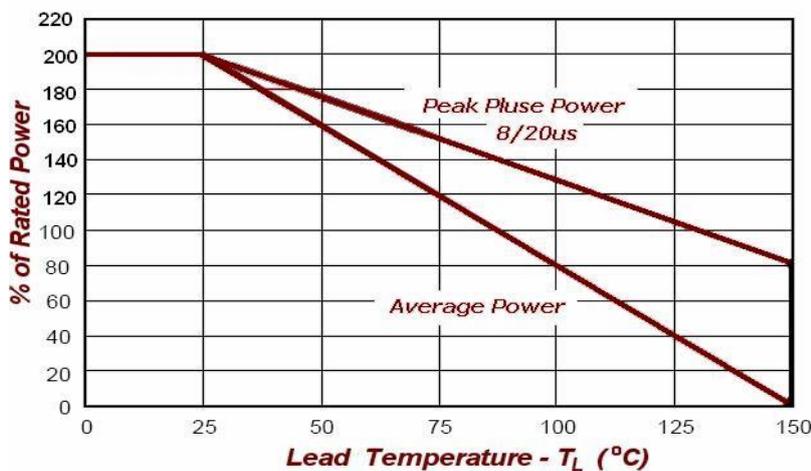
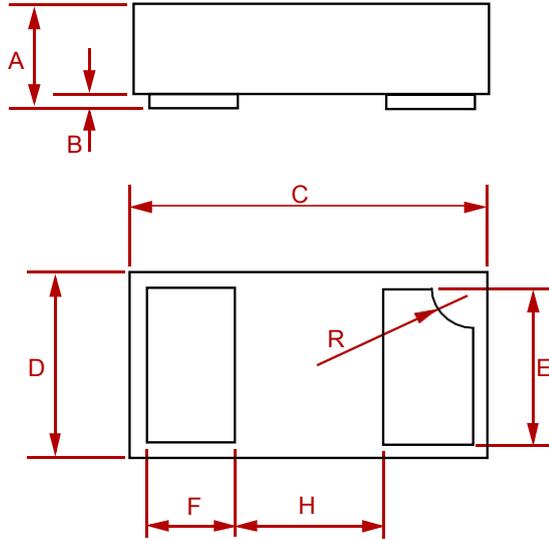


FIG2: Power Derating

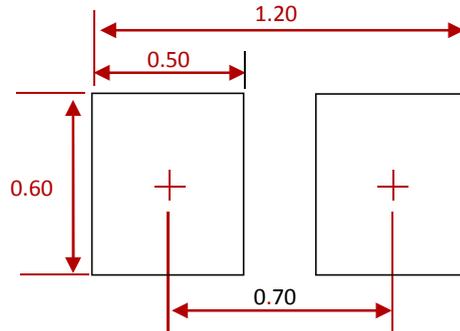


PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

Suggested Pad Layout



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
AU0511P1-MS	DFN1006	10000

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